# CD54AC139, CD74AC139 DUAL 2-LINE TO 4-LINE DECODERS/DEMULTIPLEXERS

SCHS332 - MARCH 2003

- AC Types Feature 1.5-V to 5.5-V Operation and Balanced Noise Immunity at 30% of the Supply Voltage
- Buffered Inputs
- Incorporate Two Enable Inputs to Simplify Cascading and/or Data Reception
- Speed of Bipolar F, AS, and S, With Significantly Reduced Power Consumption
- Balanced Propagation Delays
- ±24-mA Output Drive Current
   Fanout to 15 F Devices
- SCR-Latchup-Resistant CMOS Process and Circuit Design
- Exceeds 2-kV ESD Protection Per MIL-STD-883, Method 3015

#### CD54AC139...F PACKAGE CD74AC139 . . . E OR M PACKAGE (TOP VIEW) 1G 16 🛮 V<sub>CC</sub> 1A 15 🕇 2G 2 14 **1** 2A 1B 1Y0 $\Pi$ 13 T 2B 1Y1 5 12 72Y0 11 7 2Y1 1Y2 **∏** 10 2Y2 1Y3 **∏** GND 9**∏** 2Y3

## description/ordering information

The 'AC139 devices are dual 2-line to 4-line decoders/demultiplexers designed for 1.5-V to 5.5-V  $V_{CC}$  operation. These devices are designed to be used in high-performance memory-decoding or data-routing applications requiring very short propagation delay times. In high-performance memory systems, these decoders can be used to minimize the effects of system decoding. When used with high-speed memories utilizing a fast enable circuit, the delay times of these decoders and the enable time of the memory usually are less than the typical access time of the memory. This means that the effective system delay introduced by the decoders is negligible.

The active-low enable  $(\overline{G})$  input can be used as a data line in demultiplexing applications. These decoders/demultiplexers feature fully buffered inputs, each of which represents only one normalized load to its driving circuit.

#### ORDERING INFORMATION

TA	PACKA	GEŤ	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – E	Tube	CD74AC139E	CD74AC139E
_55°C to 125°C	SOIC – M	Tube	CD74AC139M	AC139M
-55 C to 125 C	SOIC - W	Tape and reel	CD74AC139M96	AC 139W
	CDIP – F	Tube	CD54AC139F3A	CD54AC139F3A

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



testing of all parameters.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include

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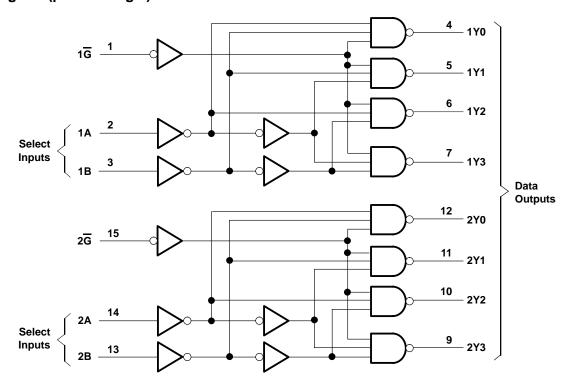


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# FUNCTION TABLE (each decoder/demultiplexer)

	INPUTS			OUT	DUTE					
G	SEL	ECT	OUTPUTS							
G	В	Α	Y0	Y1	Y2	Y3				
Н	Х	Χ	Н	Н	Н	Н				
L	L	L	L	Н	Н	Н				
L	L	Н	Н	L	Н	Н				
L	Н	L	Н	Н	L	Н				
L	Н	Н	Н	Н	Н	L				

### logic diagram (positive logic)



## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>	–0.5 V to 6 V
Input clamp current, $I_{IK}$ ( $V_I < 0 \text{ V or } V_I > V_{CC}$ ) (see Note 1)	
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0 V or V <sub>O</sub> > V <sub>CC</sub> ) (see Note 1)	
Continuous output current, I <sub>O</sub> (V <sub>O</sub> > 0 V or V <sub>O</sub> < V <sub>CC</sub> )	±50 mA
Continuous current through V <sub>CC</sub> or GND	±100 mA
Package thermal impedance, θ <sub>JA</sub> (see Note 2): E package	67°C/W
M package	73°C/W
Storage temperature range, T <sub>stq</sub>	65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
  - 2. The package thermal impedance is calculated in accordance with JESD 51-7.



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## recommended operating conditions (see Note 3)

			T <sub>A</sub> = 2	25°C	–55°( 125		–40°C to 85°C		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
Vсс	Supply voltage		1.5	5.5	1.5	5.5	1.5	5.5	V
		V <sub>CC</sub> = 1.5 V	1.2		1.2		1.2		
٧ıH	High-level input voltage	V <sub>CC</sub> = 3 V	2.1		2.1		2.1		V
		V <sub>CC</sub> = 5.5 V	3.85		3.85		3.85		
		V <sub>CC</sub> = 1.5 V		0.3		0.3		0.3	
VIL	Low-level input voltage	V <sub>CC</sub> = 3 V		0.9		0.9		0.9	V
		V <sub>CC</sub> = 5.5 V		1.65		1.65		1.65	
٧ <sub>I</sub>	Input voltage		0	VCC	0	VCC	0	VCC	V
۷o	Output voltage		0	VCC	0	VCC	0	VCC	V
ІОН	High-level output current	V <sub>CC</sub> = 4.5 V to 5.5 V		-24		-24		-24	mA
loL	Low-level output current	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		24		24		24	mA
Δt/Δν	Input transition rise or fall rate	$V_{CC} = 1.5 \text{ V to 3 V}$		50		50		50	ns/V
ΔψΔV	Input transition rise or fall rate	$V_{CC} = 3.6 \text{ V to } 5.5 \text{ V}$		20		20		20	115/V

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CON	Vcc	T <sub>A</sub> = 25°C	;	–55°( 125		–40°C to 85°C		UNIT	
				MIN MA	AΧ	MIN	MAX	MIN	MAX	
			1.5 V	1.4		1.4		1.4		
		$I_{OH} = -50  \mu A$	3 V	2.9		2.9		2.9		
			4.5 V	4.4		4.4		4.4		
Voн	$V_I = V_{IH}$ or $V_{IL}$	$I_{OH} = -4 \text{ mA}$	3 V	2.58		2.4		2.48		- v
		$I_{OH} = -24 \text{ mA}$	4.5 V	3.94		3.7		3.8		
		$I_{OH} = -50 \text{ mA}^{\dagger}$	5.5 V			3.85				
		$I_{OH} = -75 \text{ mA}^{\dagger}$	5.5 V					3.85		
			1.5 V	(	).1		0.1		0.1	
		I <sub>OL</sub> = 50 μA	3 V	(	).1		0.1		0.1	
			4.5 V	(	).1		0.1		0.1	
VOL	$V_I = V_{IH}$ or $V_{IL}$	I <sub>OL</sub> = 12 mA	3 V	0.	36		0.5		0.44	V
		$I_{OL} = 24 \text{ mA}$	4.5 V	0.	36		0.5		0.44	
		$I_{OL} = 50 \text{ mA}^{\dagger}$	5.5 V				1.65		1	
		$I_{OL} = 75 \text{ mA}^{\dagger}$	5.5 V						1.65	
lį	$V_I = V_{CC}$ or GND		5.5 V	±C	).1		±1		±1	μΑ
ICC	$V_I = V_{CC}$ or GND,	I <sub>O</sub> = 0	5.5 V		8		160		80	μΑ
C <sub>i</sub>					10		10		10	pF

<sup>†</sup> Test one output at a time, not exceeding 1-second duration. Measurement is made by forcing indicated current and measuring voltage to minimize power dissipation. Test verifies a minimum 50-Ω transmission-line drive capability at 85°C and 75-Ω transmission-line drive capability at 125°C.



# CD54AC139, CD74AC139 DUAL 2-LINE TO 4-LINE DECODERS/DEMULTIPLEXERS

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# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 1.5 V, $C_L$ = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	–55° 125		–40°( 85°		UNIT
	(1141 01)	(0011 01)	CAIACITANCE	MIN	MAX	MIN	MAX	
tPLH	A or B	Any Y	C: - 50 pE		131		119	20
<sup>t</sup> PHL	AUID	Ally f	$C_L = 50 pF$		131		119	ns
t <sub>PLH</sub>	G	Any Y	C <sub>I</sub> = 50 pF		131		119	ns
tPHL	G	Ally I	CL = 50 pr	131		119	115	

# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 3.3 V $\pm$ 0.3 V, $C_L$ = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	–55°( 125		–40°( 85°		UNIT
	(INFOT)	(001F01)	CAFACITANCE	MIN	MAX	MIN	MAX	
<sup>t</sup> PLH	A or B	Any V	C <sub>1</sub> = 50 pF	3.7	14.7	3.9	13.4	ns
<sup>t</sup> PHL	AUID	Any Y	OL = 30 pi	3.7	14.7	3.9	13.4	113
<sup>t</sup> PLH	G	Any V	C: = 50 pE	3.7	14.7	3.9	13.4	ns
<sup>t</sup> PHL	9	Any Y	$C_L = 50 \text{ pF}$	3.7	14.7	3.9	13.4	115

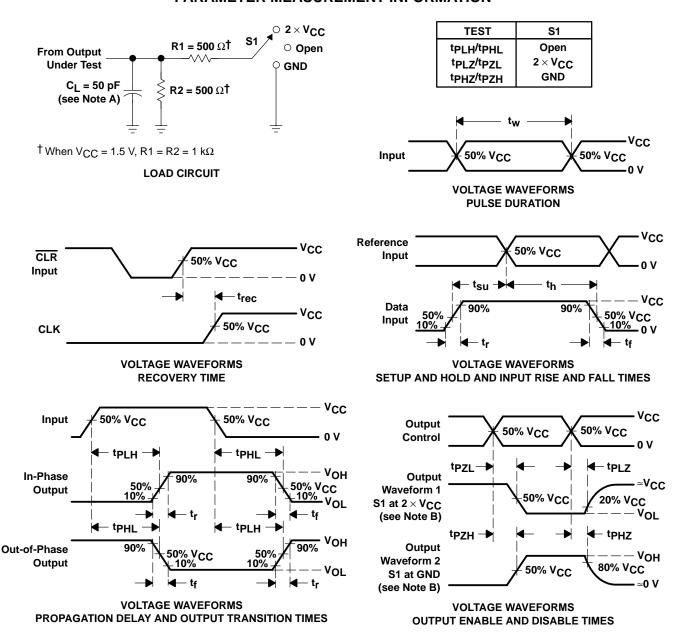
# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 5 V $\pm$ 0.5 V, $C_L$ = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM TO (INPUT) (OUTPUT)		LOAD CAPACITANCE	–55°0 125		_	–40°C to 85°C	
	(IIVI O1)	(0011 01)	CAI ACITANCE	MIN	MAX	MIN	MAX	
tPLH	A or D	Any Y	C: - 50 pF	2.6	10.5	2.8	9.5	ns
<sup>t</sup> PHL	A or B	Ally f	C <sub>L</sub> = 50 pF	2.6	10.5	2.8	9.5	115
tPLH	G	Any Y	C. = 50 pE	2.6	10.5	2.8	9.5	ne
tPHL	G	Ally f	$C_L = 50 \text{ pF}$	2.6	10.5	2.8	9.5	ns

## operating characteristics, $V_{CC} = 5 \text{ V}$ , $T_A = 25^{\circ}\text{C}$

	PARAMETER	TYP	UNIT
C <sub>pd</sub>	Power dissipation capacitance	83	pF

#### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>L</sub> includes probe and test-fixture capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_O = 50 \Omega$ ,  $t_f = 3$  ns,  $t_f = 3$  ns. Phase relationships between waveforms are arbitrary.
- D. For clock inputs, f<sub>max</sub> is measured with the input duty cycle at 50%.
- E. The outputs are measured one at a time with one input transition per measurement.
- F. tpLH and tpHL are the same as tpd.
- G. tpzL and tpzH are the same as ten.
- H. tpLZ and tpHZ are the same as tdis.
- I. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms



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#### PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
005440400504	A OTI) /F	ODID		40		Non Dallo	(6)	NI / A for Dian Tree	FF 1- 40F	005440400504	
CD54AC139F3A	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	CD54AC139F3A	Samples
CD74AC139E	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD74AC139E	Samples
CD74AC139M	LIFEBUY	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	AC139M	
CD74AC139M96	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	AC139M	Samples

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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## PACKAGE OPTION ADDENDUM

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#### OTHER QUALIFIED VERSIONS OF CD54AC139, CD74AC139:

Catalog : CD74AC139

Military: CD54AC139

NOTE: Qualified Version Definitions:

• Catalog - TI's standard catalog product

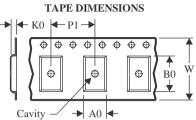
• Military - QML certified for Military and Defense Applications

## **PACKAGE MATERIALS INFORMATION**

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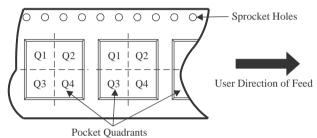
### TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

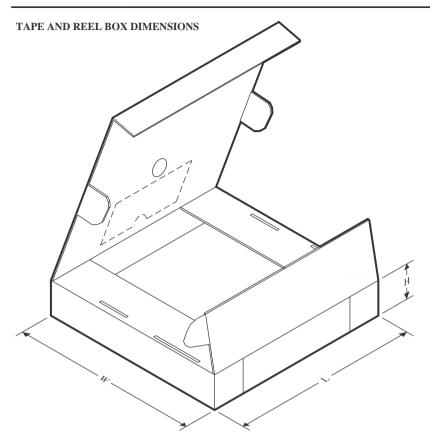


#### \*All dimensions are nominal

Device	U	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD74AC139M96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1

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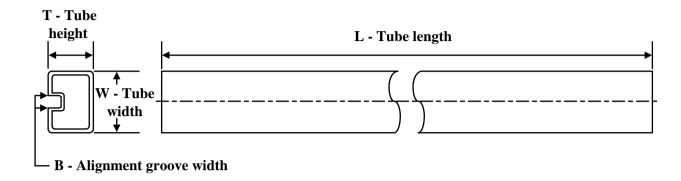
### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD74AC139M96	SOIC	D	16	2500	340.5	336.1	32.0

# **PACKAGE MATERIALS INFORMATION**

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### **TUBE**

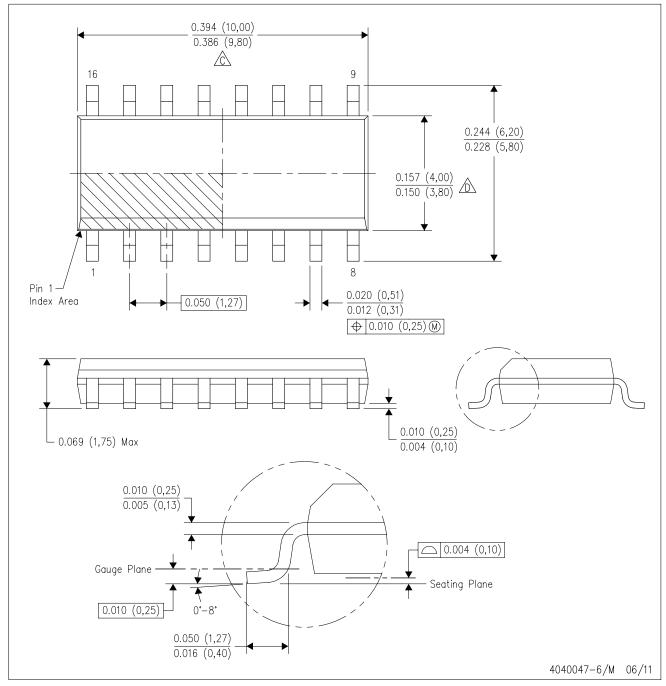


### \*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
CD74AC139E	N	PDIP	16	25	506	13.97	11230	4.32
CD74AC139E	N	PDIP	16	25	506	13.97	11230	4.32
CD74AC139M	D	SOIC	16	40	507	8	3940	4.32

# D (R-PDS0-G16)

## PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



## 14 LEADS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

# N (R-PDIP-T\*\*)

## PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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